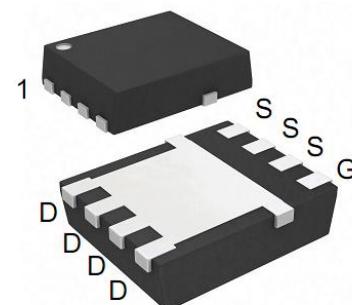


N-Channel Enhancement Mode MOSFET

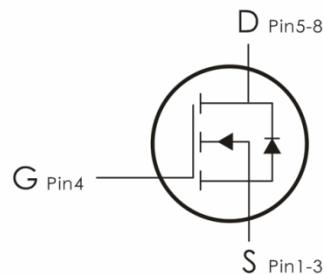
Description:

This N-Channel MOSFET uses advanced SGT technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.



Features:

- 1) $V_{DS}=60V, I_D=55A, R_{DS(on)}<10m\Omega @V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(on)}$.
- 5) Excellent package for good heat dissipation.



Absolute Maximum Ratings: ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current- $T_C=25^\circ C$ ¹	55	A
	Pulsed Drain Current ²	138	
E_{AS}	Single Pulse Avalanche Energy ⁴	30	mJ
P_D	Power Dissipation	60	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Thermal Characteristics:

Symbol	Parameter	Max	Units
R_{eJC}	Thermal Resistance,Junction to Case	2.1	°C/W
R_{eJA}	Thermal Resistance Junction to mbient	62	°C/W

Package Marking and Ordering Information:

Part NO.	Marking	Package
CSD18534Q5A	D18534	DFN5*6-8

Electrical Characteristics: ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250 \mu A$	60	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=60V$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250 \mu A$	1	---	2.5	V
$R_{DS(ON)}$	Drain-Source On Resistance	$V_{GS}=10V, I_D=20A$	---	7.5	10	$m \Omega$
		$V_{GS}=4.5V, I_D=10A$	---	10	13	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=50V, V_{GS}=0V, f=1MHz$	---	1122	---	pF
C_{oss}	Output Capacitance		---	139	---	
C_{rss}	Reverse Transfer Capacitance		---	3.8	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=50V, V_{GS}=10V, R_G=2 \Omega, I_D=10A$	---	17.9	---	ns
t_r	Rise Time		---	4	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	34.9	---	ns
t_f	Fall Time		---	5.5	---	ns
Q_g	Total Gate Charge	$V_{GS}=10V, V_{DS}=50V, I_D=10A$	---	18.4	---	nC
Q_{gs}	Gate-Source Charge		---	3.3	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	2.8	---	nC
Drain-Source Diode Characteristics						
Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{SD}	Source-Drain Diode Forward Voltage ³	$V_{GS}=0V, I_S=20A$	---	---	1.3	V
I_s	Diode forward current	$V_{GS} < V_{th}$	---	---	60	A

I_{SP}	Pulsed source current	V _{GS} <V _{th}	---	---	180	A
trr	Continuous Source Current	I _S =10 A, di/dt=100 A/μs	---	41.8	---	ns
qrr	Pulsed Source Current		---	36.1	---	nC

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) V_{DD}=50 V, R_G=50 Ω, L=0.3 mH, starting T_j=25 °C.
- 5) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.

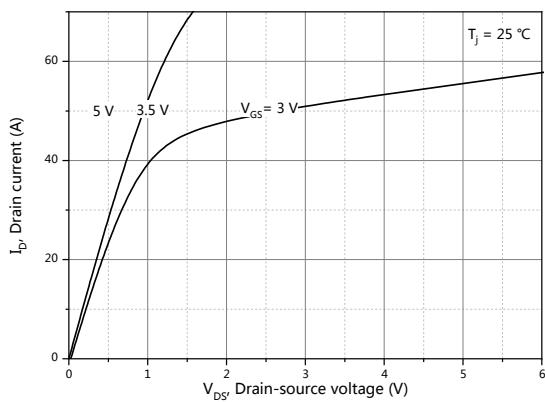
Typical Characteristics: (T_C=25°C unless otherwise noted)


Figure 1, Typ. output characteristics

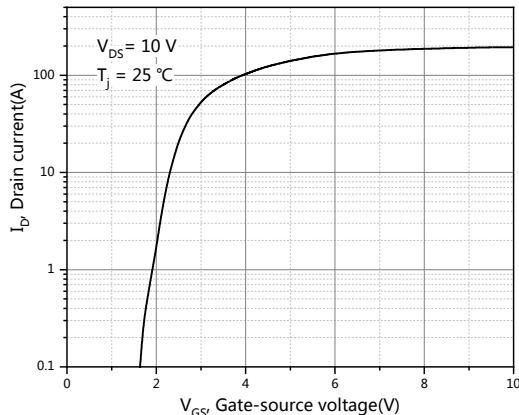


Figure 2, Typ. transfer characteristics

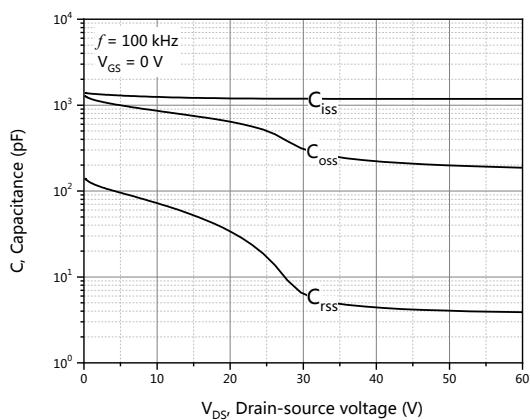


Figure 3, Typ. capacitances

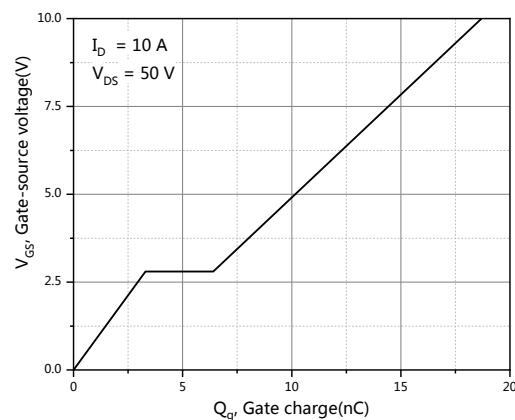


Figure 4, Typ. gate charge

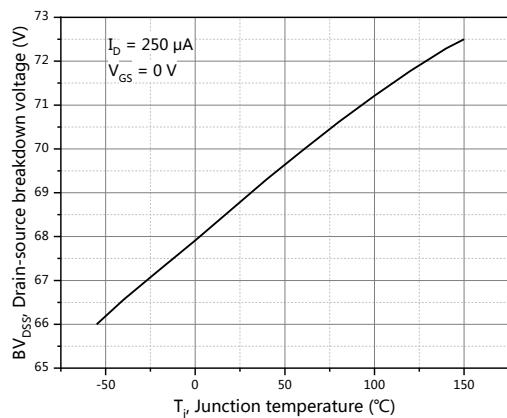


Figure 5, Drain-source breakdown voltage

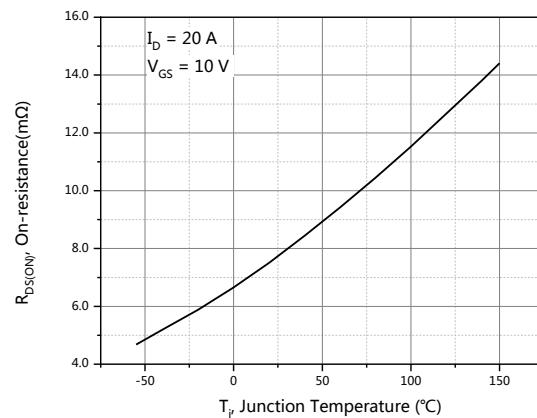


Figure 6, Drain-source on-state resistance

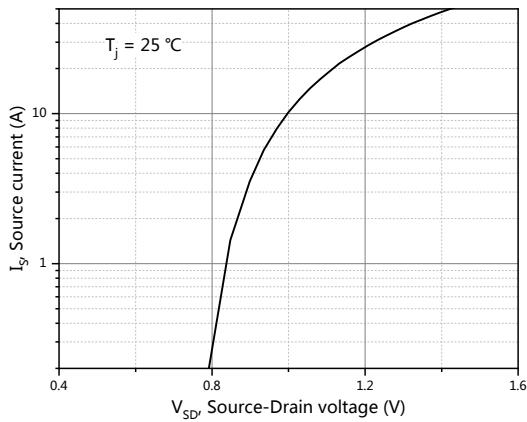


Figure 7, Forward characteristic of body diode

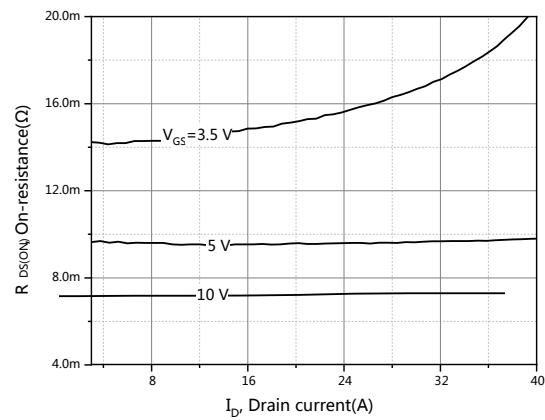


Figure 8, Drain-source on-state resistance

